

IN THE CLAIMS:

Please add new Claims 45 to 52 to read as shown below.

The following is a current listing of all the claims. This listing replaces all earlier amendments and listings of the claims, and follows the new format authorized by the U.S. Patent and Trademark Office (USPTO) as of December 2002.

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41. (Previously Added) A method for applying a liquid to a substrate by an ink jet system and detecting an abnormality of the applied liquid on the substrate, the liquid comprising a raw material of an electroconductive film and a solvent thereof, the electroconductive film being arranged to be disposed between electrodes on the substrate and having an electron emitting portion, the method comprising the steps of:

C<sup>1</sup>      applying the liquid to the substrate by the ink jet system;

forming a precursor of the electroconductive film by drying the applied liquid to evaporate the solvent; and

detecting the abnormality by examining the precursor of the electroconductive film.

42. (Previously Added) The method according to claim 41, wherein the examining includes a step of examining a forming position of the precursor.

43. (Previously Added) The method according to claim 41, wherein the examining includes a step of examining a formed shape of the precursor.

44. (Previously Added) The method according to claim 41, wherein the examining includes a step of examining a foreign substance in the precursor.

45. (New) A method for detecting an abnormality of an applied liquid on a substrate, the applied liquid comprising a solvent and a raw material of a thin film to be formed on the substrate and being applied by an ink jet system, and the thin film being a member through which electrons flow, the method comprising the steps of.

a) forming a precursor of the thin film by drying the applied liquid to evaporate the solvent; and

b) detecting the abnormality by examining the precursor of the thin film.

46. (New) A method according to claim 45, wherein step (b) includes a step of examining a position of the precursor on the substrate.

47. (New) A method according to claim 45, wherein step (b) includes a step of examining a shape of the precursor on the substrate.

48. (New) A method according to claim 45, wherein step (b) includes a step of examining whether or not the precursor contains an alien substrate.

49. (New) A method for detecting an abnormality of an applied liquid on a substrate, the applied liquid comprising a solvent and a raw material of a thin film to be formed on an electrode on the substrate and being applied onto the electrode by an ink jet system, and the thin film being a member through which electrons flow, the method comprising the steps of:

- (a) forming a precursor of the thin film by drying the applied liquid to evaporate the solvent; and
- (b) detecting the abnormality by examining the precursor of the thin film.

50. (New) A method according to claim 49, wherein step (b) includes a step of examining a shape of the precursor on the substrate.

51. (New) A method according to claim 49, wherein step (b) includes a step of examining a shape of the precursor on the substrate.

52. (New) A method according to claim 49, wherein step (b) includes a step of examining whether or not the precursor contains an alien substrate.